

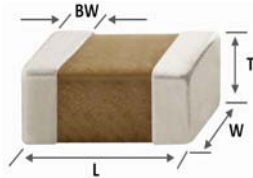
Specification of Automotive MLCC (Reference sheet)

- Supplier : Samsung Electro-Mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31B105KBHWPNE**
- Description : **CAP, 1 μ F, 50V, \pm 10%, X7R, 1206**
- AEC-Q200 Qualified

A. Dimension

● Dimension



Size	1206 inch
L	3.20 \pm 0.20 mm
W	1.60 \pm 0.20 mm
T	1.60 \pm 0.20 mm
BW	0.50 \pm 0.30 mm

B. Samsung Part Number

CL 31 B 105 K B H W P N E
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L : 3.20 \pm 0.20 mm	W : 1.60 \pm 0.20 mm
③ Dielectric	X7R	⑧ Inner electrode	Ni, Open Mode Design
④ Capacitance	1 μ F	Termination	Metal-Epoxy
⑤ Capacitance tolerance	\pm 10%	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	50 V	⑨ Product	Automotive
⑦ Thickness	1.60 \pm 0.20 mm	⑩ Special code	Normal
		⑪ Packaging	Embossed Type, 7" Reel

C. Reliability Test and Judgement condition

Test items	Performance	Test condition
High Temperature Exposure	Appearance : No abnormal exterior appearance Capacitance Change Within \pm 10 % Tan δ : 0.03 max. IR : More than 10,000 M Ω or 500 M Ω \times μ F Whichever is smaller	Unpowered, 1,000hrs @ Max. temperature Measurement at 24 \pm 2hrs after test conclusion Initial Measurement 2* Final Measurement 3*
Temperature Cycling	Appearance : No abnormal exterior appearance Capacitance Change Within \pm 10 % Tan δ : 0.03 max. IR : More than 10,000 M Ω or 500 M Ω \times μ F Whichever is smaller	1,000Cycles Initial Measurement 2* Final Measurement 3* Measurement at 24 \pm 2hrs after test conclusion 1 cycle condition : -55 \pm 0/-3 \circ C(30 \pm 3min) \rightarrow Room Temp. (1min) \rightarrow 125 \pm 3/-0 \circ C(30 \pm 3min) \rightarrow Room Temp. (1min)
Destructive Physical Analysis	No Defects or abnormalities	Per EIA 469
Humidity Bias	Appearance : No abnormal exterior appearance Capacitance Change Within \pm 12.5 % Tan δ : 0.035 max. IR : More than 500 M Ω or 25 M Ω \times μ F Whichever is smaller	1,000hrs 85 \circ C/85%RH, Rated Voltage and 1.3~1.5V, Add 100kohm resistor Initial Measurement 2* Final Measurement 4* Measurement at 24 \pm 2hrs after test conclusion The charge/discharge current is less than 50mA.
High Temperature Operating Life	Appearance : No abnormal exterior appearance Capacitance Change Within \pm 12.5 % Tan δ : 0.035 max. IR : More than 1,000 M Ω or 50 M Ω \times μ F Whichever is smaller	1,000hrs @ 125 \circ C, 200% Rated Voltage, Initial Measurement 2* Final Measurement 4* Measurement at 24 \pm 2hrs after test conclusion The charge/discharge current is less than 50mA.

	Performance	Test condition								
External Visual	No abnormal exterior appearance	Microscope (10)								
Physical Dimension	Within the specified dimensions	Using The calipers								
Mechanical Shock	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$ Tan δ , IR : Initial spec.	Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks) <table border="1"> <thead> <tr> <th>Peak value</th> <th>Duration</th> <th>Wave</th> <th>Velocity</th> </tr> </thead> <tbody> <tr> <td>1,500G</td> <td>0.5ms</td> <td>Half sine</td> <td>4.7m/sec</td> </tr> </tbody> </table> Initial Measurement 2* Final Measurement 5*	Peak value	Duration	Wave	Velocity	1,500G	0.5ms	Half sine	4.7m/sec
Peak value	Duration	Wave	Velocity							
1,500G	0.5ms	Half sine	4.7m/sec							
Vibration	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$ Tan δ , IR : Initial spec.	5g's for 20min., 12cycles each of 3 orientations, Use 8"x5" PCB 0.031" Thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10~2,000Hz. Initial Measurement 2* Final Measurement 5*								
Resistance to Solder Heat	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$ Tan δ , IR : Initial spec.	preheating : 150°C for 60~120 sec. Solder pot : 260 \pm 5°C, 10 \pm 1sec. Initial Measurement 2* Final Measurement 3*								
ESD	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$ Tan δ , IR : Initial spec.	AEC-Q200-002 or ISO/DIS10605 Initial Measurement 2* Final Measurement 4*								
Solderability	95% of the terminations is to be soldered evenly and continuously	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245 \pm 5°C b) Steam aging for 8 hours, Immerse in solder for 5s at 245 \pm 5°C c) Steam aging for 8 hours, Immerse in solder for 120s at 260 \pm 5°C solder : a solution ethanol and rosin								
Electrical Characterization	Capacitance : Within specified tolerance Tan δ : 0.025 max. IR(25°C) : More than 10,000 M Ω or 500 M Ω \times μ F Whichever is smaller IR(125°C) More than 1,000 M Ω or 10 M Ω \times μ F Whichever is smaller Dielectric Strength	*A capacitor prior to measuring the capacitance is heat treated at 150 +0/-10°C for 1hour and maintained in ambient air for 24 \pm 2 hours The Capacitance / D.F. should be measured at 25°C, 1 kHz \pm 10%, 1 \pm 0.2 Vrms I.R. should be measured with a DC voltage not exceeding Rated Voltage @25°C, @125°C for 60~120 sec. Dielectric Strength : 250% of the rated voltage for 1~5 seconds								
Board Flex	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$	Bending to the limit, 3 mm for 60 seconds 1* Initial Measurement 2* Final Measurement 5*								
Terminal Strength(SMD)	Appearance : No abnormal exterior appearance Capacitance Change Within $\pm 10\%$	18 N, for 60 sec. Initial Measurement 2* Final Measurement 5*								
Beam Load	Destruction value should be exceed 54.5 N	Beam speed : 2.5 \pm 0.25 mm/sec								
Temperature Characteristics	X7R From -55°C to 125°C, Capacitance change should be within $\pm 15\%$									

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5°C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10°C for one hour after soldering process. and then let sit for 24 \pm 2 hours at room temperature. Perform the initial measurement.
- *3 : Final measurement : Let sit for 24 \pm 2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10°C for one hour after soldering process. and then let sit for 24 \pm 2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.

 Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.

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- ② Medical equipment
- ③ Military equipment
- ④ Disaster prevention/crime prevention equipment
- ⑤ Power plant control equipment
- ⑥ Atomic energy-related equipment
- ⑦ Undersea equipment
- ⑧ Traffic signal equipment
- ⑨ Data-processing equipment
- ⑩ Electric heating apparatus, burning equipment
- ⑪ Safety equipment
- ⑫ Any other applications with the same as or similar complexity or reliability to the applications